







Agency Approval

Agency	Agency File Number
c FN °us	E14721

Product Characteristics

Blocks and Clips for Blade Fuses		
Compatible Fuses	Automotive Blade Fuses	
Electrical Specifications	Rated Voltage: 500 V	
	Rated Current: From 15 to 30 A	
Molded Parts	Insulation Block: Black Thermoplastic PET (UL94 V-0) and PA66 (UL94 V-0)	
Metal Parts	PCB Terminals: Tin Plated Cu Alloy	
Electrical	Insulation Resistance: 10,000 Megaohm Minimum at 500 VDC	
	Contact Resistance: ≤ 5 mΩ Maximum	
Ambient Temperature	-40 °C to 125 °C	

Features & Benefits

- RoHS-compliant and lead-free
- Suitable for ISO 8820-3 Type F and C blade fuses
- Special copper alloy resulting in higher current ratings
- Tin plated leads for easy soldering process
- UL Recognized to UL 4248-1 and CSA 4248.1
- Low profile design for PC board mountable terminals for Pb-free wave soldering process

Additional Information







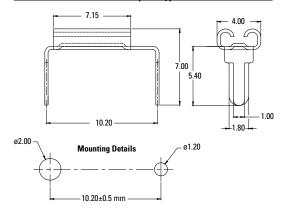
Resources

Accessories

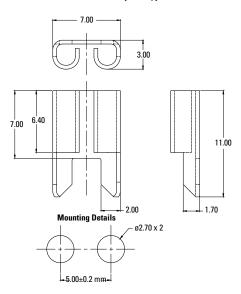
Samples

Product Dimensions (in mm)

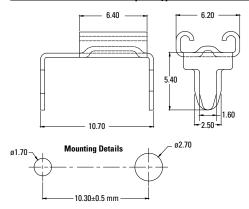
01000059Z Horizontal Fuse Clip for Type F or MINI blade fuses



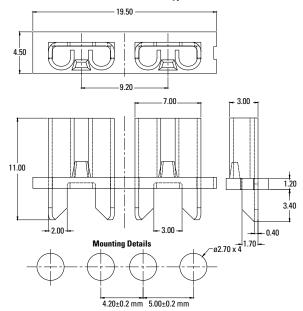
01000061Z Vertical Fuse Clip for Type C or ATFO blade fuses



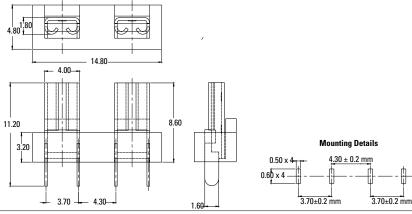
01000060Z Horizontal Fuse Clip for Type C or ATFO blade fuses



01000062Z Low Profile Fuse Block for Type C or ATFO blade fuses



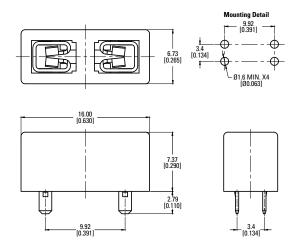
01000063Z Low Profile Fuse Block for Type F or MINI blade fuses



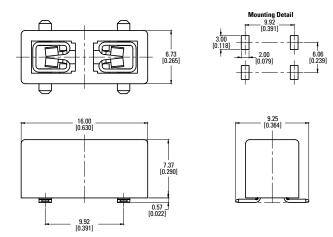


Product Dimensions in mm [inch]

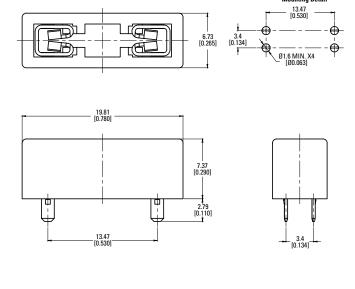
01000064Z For Mini Fuse Through Hole Installation



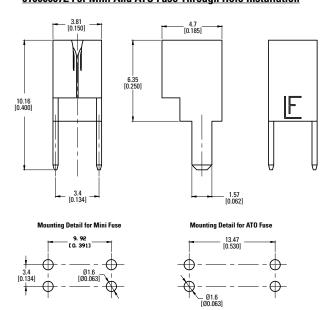
01000065Z For Mini Fuse Surface Mount Installation



01000066Z For ATO Fuse Through Hole Installation



01000067Z For Mini And ATO Fuse Through Hole Installation



Soldering Parameters-Wave Soldering

Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flex Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum	100 °C
Temperature Maximum	150 °C
Preheat Time	60-180 seconds
Solder Pot Temperature	260 °C Maximum
Solder Dwell Time	2-5 seconds

Recommended Hand-Solder Parameters:

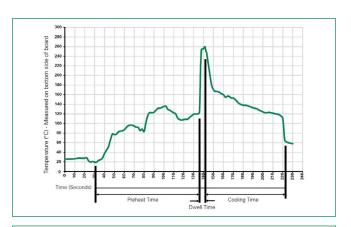
Solder Iron Temperature: 350 °C +/- 5 °C

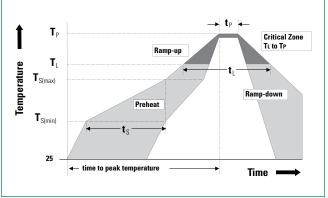
Heating Time: 5 seconds max.

Note: These devices are not recommended for IR or Convection Reflow process.

Average Ramp-Up Rate (Ts _{max} to TP) 3 °C/second max.		
Preheat	Temperature Min (Ts _{min})	150 °C
	Temperature Max (Ts _{max})	200 °C
	Time (Ts _{min} to Ts _{max})	60-120 seconds
Time maintained above	Temperature (T _L)	217 °C
	Time (t _L)	60-105 seconds
Peak Temperature (T _P)		255 °C
Time within 5 °C of actual Peak Temperature ($t_{\rm p}$)		5 seconds max.
Ramp-Down Rate		6 °C/second max.
Time 25 °C to Peak Temperature		8 minutes max.

Note: For SMD version, a bake process for 30 minutes at 125 °C is suggested prior to be subjected to reflow soldering process.





Ordering Information

3		
Ordering PN	Description	Packaging
01000059Z	Horizontal Fuse Clip For Mini Fuse 15 Amp.	1000 pieces, bulk pack
01000060Z	Horizontal Fuse Clip For ATO Fuse 30 Amp.	1000 pieces, bulk pack
01000061Z	Vertical Fuse Clip For ATO Fuse 30 Amp.	1000 pieces, bulk pack
01000062Z	Low Profile Fuse Block For ATO Fuse 30 Amp.	1000 pieces, bulk pack
01000063Z	Low Profile Fuse Block For Mini Fuse 20 Amp.	1000 pieces, bulk pack
01000064Z	High Profile Block Mini Fuse THT 30 Amp.	1000 pieces, bulk pack
01000065Z	High Profile Block Mini Fuse SMT 30 Amp.	1000 pieces, bulk pack
01000066Z	High Profile Block ATO Fuse THT 30 Amp.	1000 pieces, bulk pack
01000067Z	Vertical Fuseclip for Mini-ATO Fuses 30 Amp.	1000 pieces, bulk pack

Panel thickness minimum 0,8 mm and maximum 2.5 mm

